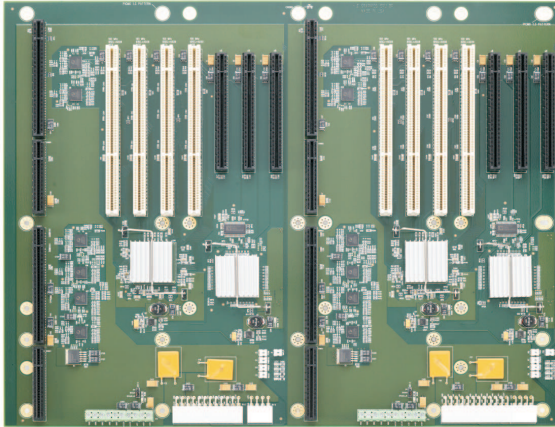


BP2S6929

TWO-SEGMENT PCI EXPRESS / PCI-X BACKPLANE

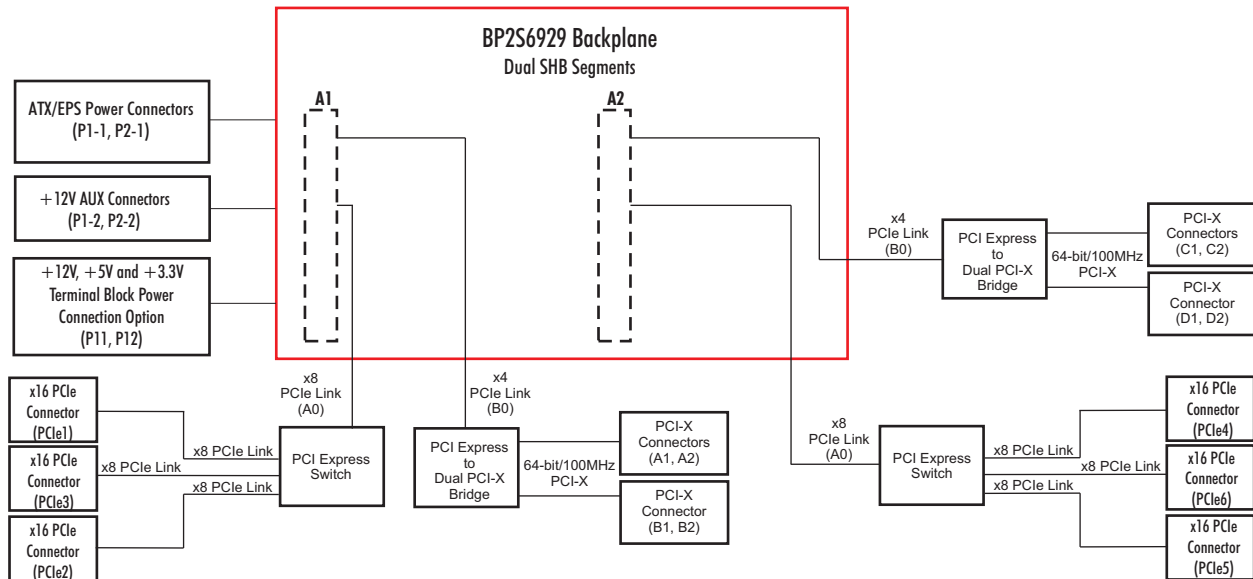


FEATURES

- 20-slot form factor supports up to two PICMG® 1.3 graphics or server-class system host boards
- Three x16 PCI Express® mechanical slots per segment
- Four 64-bit/100MHz PCI-X card slots per segment
- Optimized for use with Trenton high-performance PICMG 1.3 system host boards
- Ideal for cluster computing system applications where processing scalability and system longevity are key requirements
- Used in the Trenton TRC5001 and TRC5002 19" rackmount computers
- Right-angle ATX/EPS and +12V AUX power connector options
- +12V, +5 and +3.3V terminal block connector options
- Five-year factory warranty
- Made in U. S. A.



BLOCK DIAGRAM:



TWO-SEGMENT PCI EXPRESS BACKPLANE:

The PCI Express® link design of the Trenton BP2S6929 backplane enables the use of combo, graphics or server-class SHBs without the need of specific build options. Each segment supports either a graphics-class or server-class SHB, three PCI Express (PCIe) and four 64-bit/100MHz PCI-X option card slots. All the PCI Express slots are x16 mechanical slots and each PCIe slot is driven with a x8 PCI Express link. Each backplane segment has right-angle, ATX/EPS and 12V AUX power connectors. The backplane can also be ordered with supplemental terminal blocks for connecting additional +12V, +3.3V and +5V power.

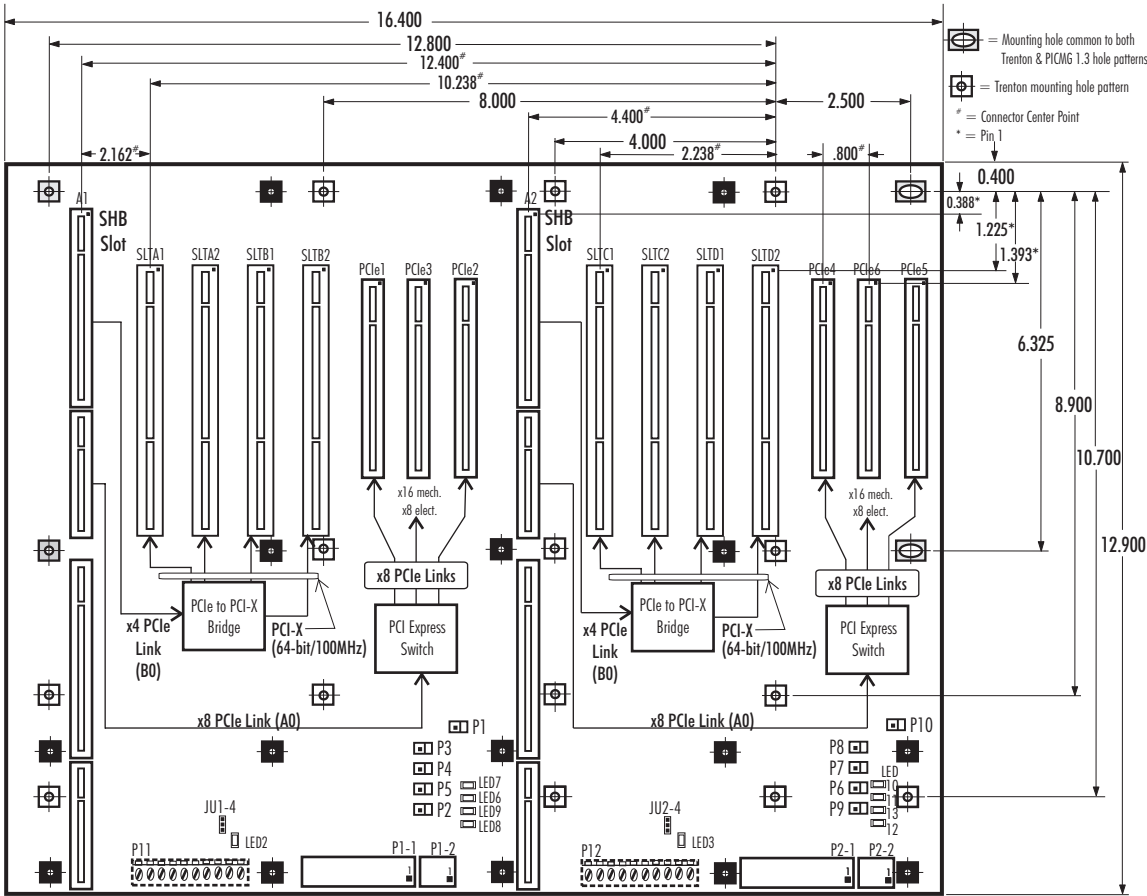
APPLICATION EXAMPLES:

Cluster computing applications that require the processing capabilities of multiple single or dual processor single board computers working independently in a rugged 4U, 19" rackmount chassis are typical system configurations for the backplane. The combination of PCI-X and PCI Express option card slots maximizes option card flexibility in robust system designs. A few application examples for the two segment backplane include cryptography, aircraft communications and control, missile telemetry, complex fabrication machines used in silicon wafer processing, oil and mineral exploration and automatic toll-booths.

BACKPLANE MODEL: BP2S6929

| MODEL# | MODEL NAME | DESCRIPTION |
|----------|--------------|--|
| 6929-007 | BP2S6929-CRA | Graphics-class, Right-angle EPS/ATX and +12V AUX connectors plus Terminal Blocks |
| 6929-009 | BP2S6929-RAC | Graphics-class, Right-angle EPS/ATX and +12V AUX connectors only |
| 6929-017 | BP2S6929-TRA | Graphics-class, Right-angle EPS/ATX and Terminal Blocks (no +12V AUX connectors) |

BP2S6929 LAYOUT - TRENTON MOUNTING HOLE PATTERN DIMENSIONS:



SUGGESTED TRENTON PICMG 1.3 SHBs:

DUAL PROCESSOR SYSTEM HOST BOARDS

BXT7059 JXT6966 MCXT
NLT SLT

SINGLE PROCESSOR SYSTEM HOST BOARDS

TSB7053 TQ9 TML
BXTS7059 JXTS6966 MCXI
NLI SLI

ENVIRONMENTAL SPECS.:#

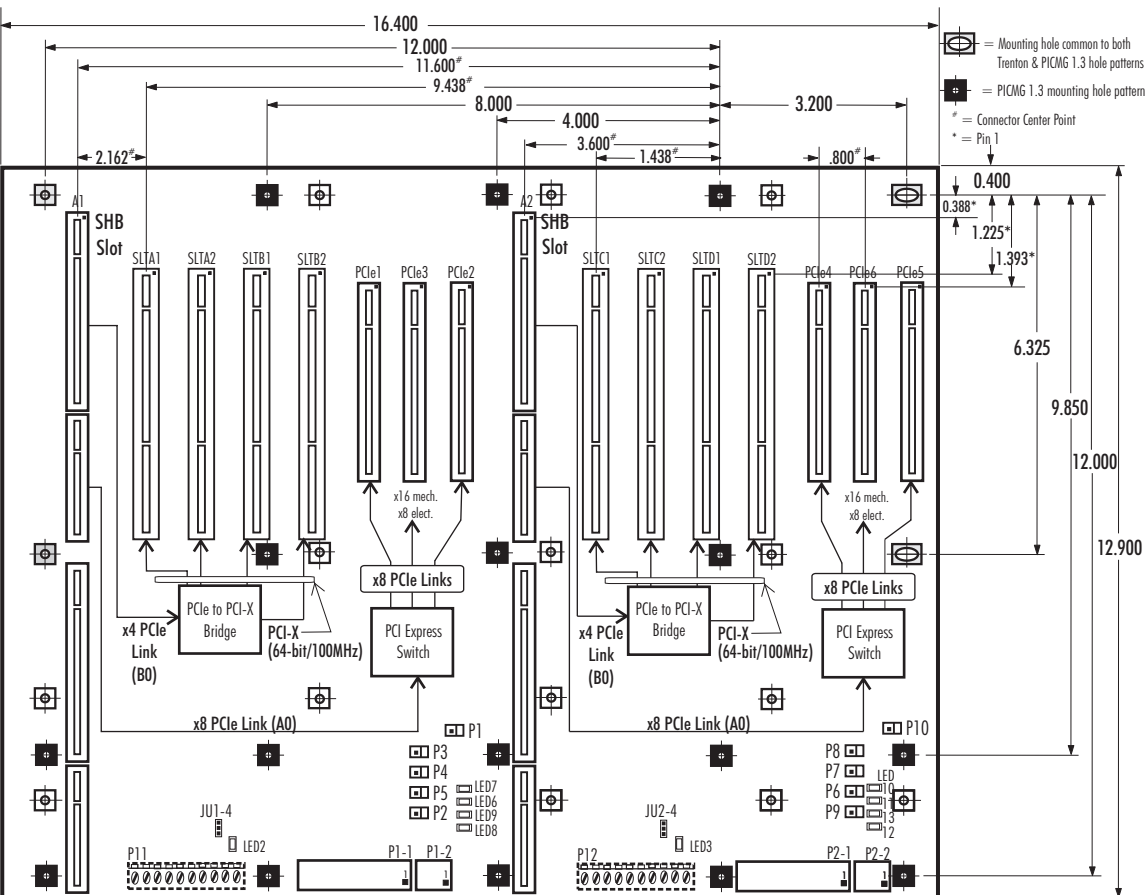
Operating Temp.: 0° C. to 60° C
Storage Temp.: -20° C. to 70° C
Humidity: 5% to 90%, non-condensing
Environmental specifications for system host boards / single board computers are usually lower than those of the backplane. Check with your SHB/SBC vendor.

The Trenton BP2S6929 is a lead-free, RoHS compliant backplane.

This backplane is designed to meet worldwide EMI emissions requirements, CE conformity and immunity standards. Contact Trenton for the specific standard numbers this product.

The Trenton BP2S6929 backplane is designed for UL60950 and CAN/CSA C22.2 No. 60950-00.

BP2S6929 LAYOUT - PICMG 1.3 MOUNTING HOLE PATTERN DIMENSIONS:



Notes: Dotted lines indicate connectors that are populated based on model name and number.

Mounting holes: 0.156" diameter
Nominal PCB thickness: 0.080"
All dimensions are inches.

*NOTE: The photo of the 6929 backplane shown on page one is provided for illustrative purposes only. Actual connector locations are illustrated in the backplane layout drawings and on the Trenton website.

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